

MSP430F13x/14x/14x1 Device Erratasheet

Current Version

Devices	Rev:	ADC1	ADC5	ADC7	ADC8	ADC9	ADC10	ADC18	BCL5	BSL3	BSL4	BSL5	CPU4	FLASH13	PORT3	RES3	RES4	TA12	TA16	TB1	TB2	TB3	TB4	TB14	TB15	TB16	US13	US15	WDG2
MSP430F133	S	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
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MSP430F135	S	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
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MSP430F147	S	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
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MSP430F1471	S								✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
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MSP430F148	S	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
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MSP430F1481	S								✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
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MSP430F149	S	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
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MSP430F1491	S								✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
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Note: See Appendix for prior revisions

Package Markings

PM64: LQFP(PM) 64-pin



YM = Year and Month Date Code
 LLLL = LOT Trace Code
 S = Assembly Site Code
 # = DIE Revision
 o = PIN 1

PAG64: TQFP(PAG) 64-pin



YM = Year and Month Date Code
 LLLL = LOT Trace Code
 S = Assembly Site Code
 # = DIE Revision
 o = PIN 1

Package Markings (continued)

RTD64: QFN(RTD) 64-pin

○ M430Fxxx	TI = TI
TI YMS	YM = Year and Month Date Code
LLLL #	LLLL = LOT Trace Code
	S = Assembly Site Code
	# = DIE Revision
	o = PIN 1

Detailed Bug Description

ADC1 ADC1 - Bug description:

Module: ADC12, Function: Start of conversion

In single conversion/sequence mode (CONSEQ = 0/1), the next conversion can be started with ADC12SC. It is not required to clear ENC before setting ADC12SC. This is opposite to the specification.

Workaround:
None

ADC5 ADC5 - Bug description:

Module: ADC12, Function: Interrupt flag register

ADC12 interrupt flag may not be set when the CPU simultaneously accesses the ADC12IFG register.

Workaround:
There is no need to access the interrupt flag register to process interrupt situations. Please use the ADC12IV register to identify the interrupt event. The corresponding flag bits will be reset automatically. Additional details are discussed in the device family User's Guide.

ADC7 ADC7 - Bug description:

Module: ADC12, Function: Conversion Time Overflow

The timing overflow flag is set when in sequence mode (CONSEQ = 1 or 3) and MSC = 0, even if no overflow has occurred.

Workaround:
Verify correct timing and do not enable Conversion-Time Overflow interrupt.

ADC8 ADC8 - Bug description:

Module: ADC12, Function: Interrupt flag register

Clearing flags in the interrupt flag register with a CPU instruction will not clear the latest interrupt flag.

Workaround:
Clear interrupt flags by accessing the conversion-memory registers.

Detailed Bug Description (continued)

ADC9 ADC9 - Bug description:

Module: ADC12, Function: Interrupt vector register

If the ADC12 uses a different clock than the CPU (MCLK) and more than one ADC interrupt is enabled, the ADC12IV register content may be unpredictable for one clock cycle. This will happen if, during the execution of an ADC interrupt, another ADC interrupt with higher priority occurs.

Workaround:

- Read out ADC12IV twice and use only when values are equal.
- Use ADC12IFG to determine which interrupt has occurred.

ADC10 ADC10 - Bug description:

Module: ADC12, Function: Unintended start of conversion

Accessing ADC12OVIE or ADC12TOVIE at the end of an ADC12 conversion with BIS/BIC commands can cause the ADC12SC bit to be set again right after it was cleared. This might start another conversion if ADC12SC is configured to trigger the ADC (SHS = 0).

Workaround:

If ADC12SC is configured to trigger the ADC, the control bits ADC12OVIE and ADC12TOVIE should only be modified when the ADC is not busy (ADC12BUSY = 0).

ADC18 ADC18 - Bug description:

Module: ADC12, incorrect conversion result in extended sample mode

The ADC12 conversion result can be incorrect in the case where the extended sample mode is selected (SHP = 0), the conversion clock is not the internal ADC12 oscillator (ADC12SSEL > 0), and one of the following two conditions is true:

- 1.) The extended sample input signal SHI is asynchronous to the clock source used for ADC12CLK and the undivided ADC12 input clock frequency exceeds 3.15 MHz.
or
- 2.) The extended sample input signal SHI is synchronous to the clock source used for ADC12CLK and the undivided ADC12 input clock frequency exceeds 6.3 MHz.

Workaround:

- 1.) Use the pulse sample mode (SHP = 1).
or
- 2.) Use the ADC12 internal oscillator as the ADC12 clock source.
or
- 3.) Limit the undivided ADC12 input clock frequency to 3.15 MHz.
or
- 4.) Use the same clock source (such as ACLK or SMCLK) to derive both SHI and ADC12CLK, in order to achieve synchronous operation, and also limit the undivided ADC12 input clock frequency to 6.3 MHz.

Detailed Bug Description (continued)

BCL5 BCL5 - Bug description:

Module: Basic Clock, Function: RSELx bit modifications can generate high frequency spikes on MCLK

When DIVMx = 00 or 01 the RSELx bits of the Basic Clock Module are incremented or decremented in steps of 2 or greater, the DCO output may momentarily generate high frequency spikes on MCLK, which may corrupt CPU operation. This is not an issue when DIVMx = 10 or 11.

Workaround:

Set DIVMx = 10 or 11 to divide the MCLK input prior to modifying RSELx. Once the RSELx bits are configured as desired, the DIVMx setting can be changed back to the original selection.

BSL3 BSL3 - Bug description:

Module: Bootstrap Loader

Receiving frames with a checksum value equal to a legal address can change the content of this address or the bootstrap loader may stop operation.

Workaround:

Software workaround is available.

BSL4 BSL4 - Bug description:

Module: Bootstrap Loader, Function: Flash memory cannot be programmed

The bootstrap loader SW cannot program the flash memory.

Workaround:

Software workaround is available.

BSL5 BSL5 - Bug description:

Module: Bootstrap Loader

If the RST/NMI pin is configured to NMI, the bootstrap loader may not be started. Unpredictable operations will result.

Workaround:

None

CPU4 CPU4 - Bug description:

Module: CPU, Function: PUSH #4, PUSH #8

The single operand instruction PUSH cannot use the internal constants (CG) 4 and 8. The other internal constants (0, 1, 2, -1) can be used. The number of clock cycles is different:

PUSH #CG uses address mode 00, requiring 3 cycles, 1 word instruction

PUSH #4/#8 uses address mode 11, requiring 5 cycles, 2 word instruction

Workaround implemented in assembler.

No fix planned.

Detailed Bug Description (continued)

FLASH13 FLASH13 - Bug description:

Module: Flash, Function: Mass Erase

A mass erase time of >200 ms is required. This is not covered by the flash controller.

Workaround possible by executing multiple mass erase cycles.

PORT3 Port3 - Bug description:

Module: PORT1/2, Function: Port interrupts can get lost

Port interrupts can get lost if they occur during CPU access of the P1IFG and P2IFG registers.

Workaround:
None

RES3 RES3 - Bug description:

Module: General, Function: Reset

When RST/NMI is held low during power up of V_{CC} , some internal drivers are not reset correctly. This may result in a high I_{CC} current until the internal power-on signal has generated one clock cycle to reset the internal drivers. This limits the time when the excess current can occur to the time the power up circuit is active.

Workaround:
None

RES4 RES4 - Bug description:

Module: General, Reset, No reset if external resistor exceeds certain value

No reset of the device is performed if the external pull-down resistor on RST/NMI pin is above a certain limit. The limits are:

$V_{CC} = 1.8\text{ V}$: maximum pull-down resistor = 12 k Ω

$V_{CC} = 3.0\text{ V}$: maximum pull-down resistor = 5 k Ω

$V_{CC} = 3.6\text{ V}$: maximum pull-down resistor = 2.5 k Ω

In addition, a higher current consumption occurs during high/low RST/NMI signal transition when using improper resistors.

Workaround:
Use external pull-down resistors below the mentioned values or directly drive RST/NMI low to generate a reset.

Detailed Bug Description (continued)

TA12 TA12 - Bug description:

Module: Timer_A, Function: Interrupt is lost (slow ACLK)

Timer_A counter is running with slow clock (external TACLK or ACLK) compared to MCLK. The compare mode is selected for the capture/compare channel and the CCRx register is incremented by 1 with the occurring compare interrupt (if TAR = CCRx).

Due to the fast MCLK the CCRx register increment ($CCRx = CCRx + 1$) happens before the Timer_A counter has incremented again. Therefore, the next compare interrupt should happen at once with the next Timer_A counter increment (if TAR = CCRx + 1). This interrupt gets lost.

Workaround:

Switch capture/compare mode to capture mode before the CCRx register increment. Switch back to compare mode afterwards.

TA16 TA16 - Bug description:

Module: Timer_A, Function: First increment of TAR erroneous when IDx > 00

The first increment of TAR after any timer clear event (POR/TACLK) happens immediately following the first positive edge of the selected clock source (INCLK, SMCLK, ACLK or TACLK). This is independent of the clock input divider settings (ID0, ID1). All following TAR increments are performed correctly with the selected IDx settings.

Workaround:

None

TB1 TB1 - Bug description:

Module: Timer_B, Function: "Equal mode" when grouping compare latches

The "equal mode" for loading the compare latches (CLLD = 3) cannot be used when compare latches are grouped (TBCLGRP > 0).

No workaround possible.

TB2 TB2 - Bug description:

Module: Timer_B, Function: Interrupt is lost (slow ACLK)

Timer_B counter is running with slow clock (external TBCLK or ACLK) compared to MCLK. The compare mode is selected for the capture/compare channel and the CCRx register is incremented by 1 with the occurring compare interrupt (if TBR = CCRx).

Due to the fast MCLK, the CCRx register increment ($CCRx = CCRx + 1$) happens before the Timer_B counter has incremented again. Therefore, the next compare interrupt should happen at once with the next Timer_B counter increment (if TBR = CCRx + 1). This interrupt gets lost.

Workaround:

Switch capture/compare mode to capture mode before the CCRx register increment. Switch back to compare mode afterwards.

Detailed Bug Description (continued)

TB3 TB3 - Bug description:

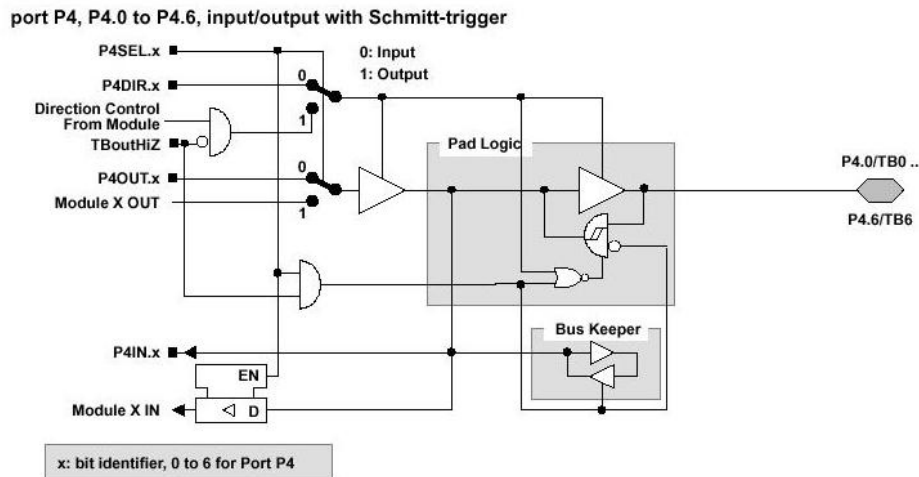
Module: Timer_B, Function: Port is switched to tristate independent of selected function

Incorrect tristate function of Ports P4.0/TB0 through P4.6/TB6 (TBoutHiZ control). If TBoutHiZ is set to high, all ports P4.0/TB0 through P4.6/TB6 are set to tristate, independent of the P4SEL.x control signals. This means a port P4.x is switched to tristate with TBoutHiZ, even if it is not selected for Timer_B function.

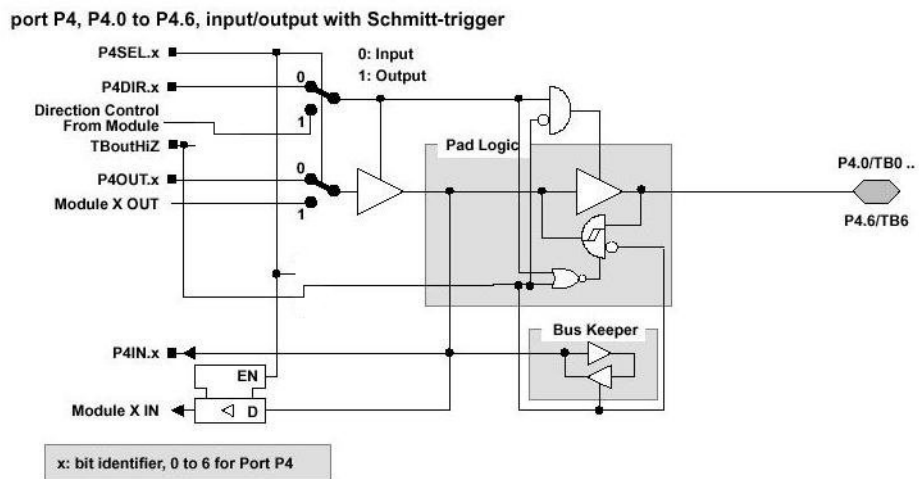
In addition, the ports P4.0/TB0 through P4.6/TB6 are switched to tristate with TBoutHiZ, even if the port direction (direction control from module) is set to input. This is in accordance with the specification description but, nevertheless, is an unexpected behavior.

No workaround.

Port function as specified:



Port realization with TB3 bug:



TB4 TB4 - Bug description:

Module: Timer_B, Function: Group function

If the shadow registers are organized in groups (SHR = 1, 2, or 3) one shadow register is not loaded correctly. This happens, when the last CCRx register within a group is loaded exactly at the same time as the timer counter reaches the event for loading the shadow registers (TBR = 0 or TBR = CCR0).

Workaround:

Ensure that all CCRx-registers within a group are loaded before the shadow register load event occurs.

TB14 TB14 - Bug description:

Module: Timer_B, Function: PWM output

The PWM output unit may behave erroneously if the condition for changing the PWM output (EQUx or EQU0) and the condition for loading the shadow register TBCLx happens at the same time. Depending on the load condition for the shadow registers (CLLD bits in TBCCTLx), there are four different possible error conditions:

1. Change CCRx register from any value to CCRx = 0
(e.g., sequence for CCRx = 4 3 2 0 0 0)
2. Change CCRx register from CCRx = 0 to any value
(e.g., sequence for CCRx = 0 0 0 2 3 4)
3. Change CCRx register from any value to current SHD0 (CCR0) value
(e.g., sequence for CCRx = 4 2 5 SHD0 3 8)
4. Change CCRx register from current SHD0 (CCR0) value to any value
(e.g., sequence for CCRx = 4 2 SHD0 5 3 8)

Workaround:

No general workaround available.

TB15 TB15 - Bug description:

Module: Timer_B3, Function: "Grouping Compare Latch" modes with TBCLx = 2 or 3 are not useable

For Timer_B3, "Gouping Compare Latch" modes with control bits TBCLx = 10 or 11 (Bits 14, 13 in TBCTL register) are not useable. If one of these settings are used, no load of any Compare Latch TBCLx will happen.

Workaround:

None (use only TBCLx = 00 or 01 for reliable module operation.)

Detailed Bug Description (continued)

TB16 TB16 - Bug description:

Module: Timer_B, Function: First increment of TBR erroneous when IDx > 00

The first increment of TBR after any timer clear event (POR/TBCLR) happens immediately following the first positive edge of the selected clock source (INCLK, SMCLK, ACLK or TBCLK). This is independent of the clock input divider settings (ID0, ID1). All following TBR increments are performed correctly with the selected IDx settings.

Workaround:
None

US13 US13 - Bug description:

Module: USART0, USART1, Function: Unpredictable program execution

USART interrupts requested by URXS can result in unpredictable program execution if this request is not served within two bit times of the received data.

Workaround:
Ensure that the interrupt service routine is entered within two bit times of the received data.

US15 US15 - Bug description:

Module: USART0, USART1, Function: UART receive with two stop bits

USART hardware does not detect a missing second stop bit when SPB = 1. The Framing Error Flag (FE) will not be set under this condition and erroneous data reception may occur.

Workaround:
None (Configure USART for a single stop bit, SPB = 0)

WDG2 WDG2 - Bug description:

If a key violation is caused by incorrectly accessing a flash control register, the watchdog interrupt flag is set in addition to a correctly generated PUC.

Workaround:
None

Detailed Bug Description

ADC11 ADC11 - Bug description:

Module: ADC12, Function: Temporary leakage current after conversion

The ADC12 causes temporary leakage current after a completed conversion. Duration and magnitude of the leakage current depends on parasitic effects.

Workaround:
None

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